

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A method of forming a substrate made of a Group III-V nitride compound including at least one element from Group IIIB elements and at least nitrogen (N) from Group VB elements, wherein the substrate is grown on a growth ~~substrate~~base with a thickness of smaller than or equal to 100 μm , the substrate having a thickness of larger than or equal to 200 μm and a curvature smaller than or equal to 0.03 cm^{-1} , the curvature being caused by a difference in thermal expansion coefficients of the growth base and the substrate.

2. (Original) A method of forming a substrate according to claim 1, wherein the growth base made of one selected from a group consisting of sapphire, silicon carbide, spinel, gallium arsenide and silicon is used.

3. (Original) A method of forming a substrate according to claim 1, wherein the substrate made of gallium nitride (GaN) is grown.

4. (Original) A method of forming a substrate according to claim 1, wherein the substrate is grown by means of hydride vapor phase deposition, halide vapor phase deposition or metal organic chemical vapor deposition.

5. (Currently Amended) A method of forming a substrate according to claim 1, wherein the substrate is ~~grown while doping~~doped with impurities.

6. (Original) A method of forming a substrate according to claim 5, wherein at least one selected from a group consisting of carbon (C), silicon (Si), germanium (Ge), tin (Sn), sulfur (S), selenium (Se) and tellurium (Te), or at least one selected from a group consisting of carbon, silicon, germanium, tin, beryllium (Be), magnesium (Mg), calcium (Ca), zinc (Zn) and cadmium (Cd) is doped as the impurities.

7. (Original) A method of forming a substrate according to claim 1, further comprising a step of removing the growth base.

8. (Original) A method of forming a substrate according to claim 7, wherein the growth base is removed by means of etching, lapping or heat application.

9. (Original) A method of forming a substrate according to claim 7, further comprising a step of forming a protecting film to cover the substrate prior to the step of removing the growth base.

10. (Original) A method of forming a substrate according to claim 1, further comprising a step of flattening a surface of the substrate.